

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



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MOV



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Product data sheet

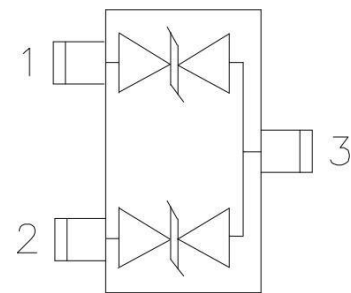
[www.msksemi.com](http://www.msksemi.com)

## Features

- Ultra low leakage: nA level
- Operating voltage: 24V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 30\text{kV}$
    - Contact discharge:  $\pm 30\text{kV}$
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 5A (8/20 $\mu\text{s}$ )
- RoHS Compliant
- AEC-Q101 Compliant



## Pin Configuration



## SOT-23

## Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

## Mechanical Characteristics

- Package: SOT-23
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel: 3,000 pcs
- Reel Size: 7 inch

## Electrical Characteristics (TA=25°C unless otherwise specified)

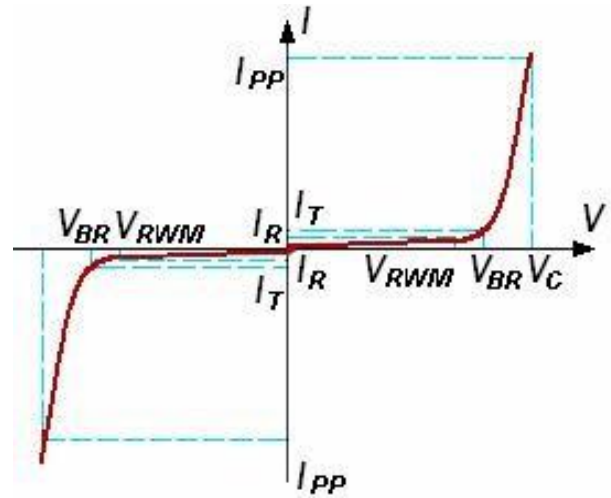
P/N	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I <sub>T</sub> (mA)	V <sub>C</sub> @1A	V <sub>C</sub>		I <sub>R</sub> $\mu\text{A}$ (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
MSESD2CAN	24	27	1	40	50	8	0.2	25

## Absolute Maximum Ratings (T<sub>amb</sub>=25°C unless otherwise specified)

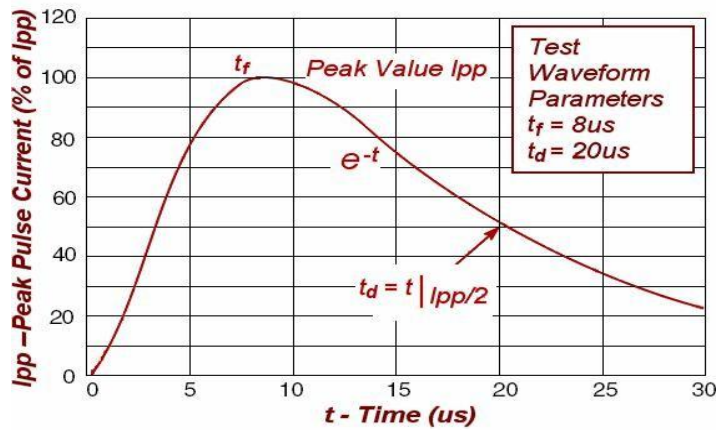
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 $\mu\text{s}$ )	P <sub>pp</sub>	450	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	$\pm 30$	Kv
ESD per IEC 61000-4-2 (Contact)		$\pm 30$	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	°C

**Electrical Parameter**

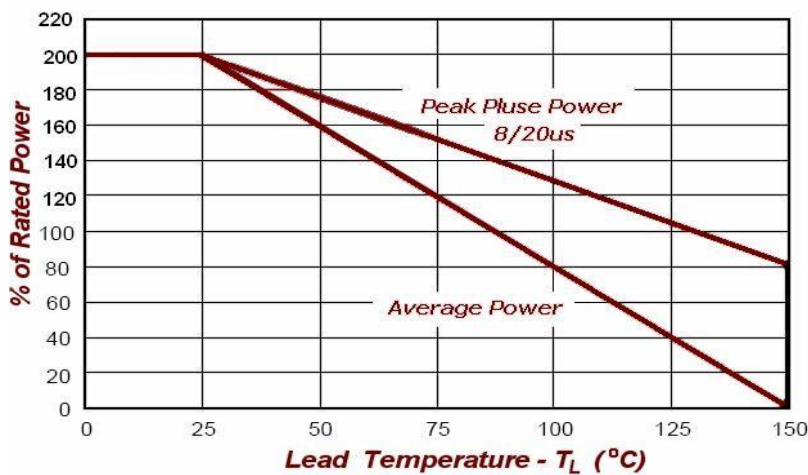
Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$I_T$	Test Current
$V_{BR}$	Breakdown Voltage @ $I_T$



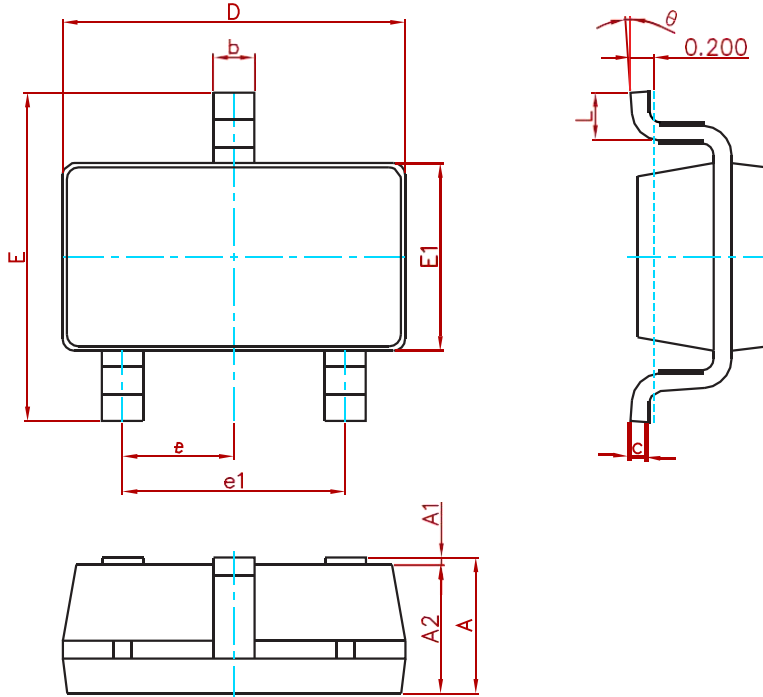
**FIG1: Pulse Waveform**



**FIG2: Power Derating**

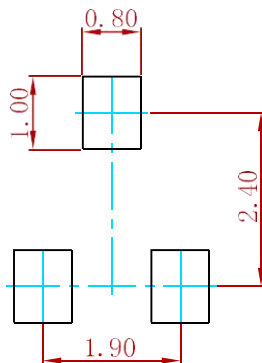


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

**Suggested Pad Layout**



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance: ± 0.05mm.  
 3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
MSESD2CAN	SOT-23	3000

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